

Title (en)

ELECTROLESS COPPER PLATING COMPOSITIONS AND METHODS FOR ELECTROLESS PLATING COPPER ON SUBSTRATES

Title (de)

ZUSAMMENSETZUNGEN ZUR STROMLOSEN VERKUPFERUNG UND VERFAHREN ZUR STROMLOSEN VERKUPFERUNG AUF SUBSTRATEN

Title (fr)

COMPOSITIONS DE PLACAGE ÉLECTROLYTIQUE DE CUIVRE ET PROCÉDÉS DE PLACAGE ÉLECTROLYTIQUE DE CUIVRE SUR DES SUBSTRATS

Publication

**EP 3581677 A1 20191218 (EN)**

Application

**EP 19179167 A 20190607**

Priority

US 201862685353 P 20180615

Abstract (en)

Stable electroless copper plating baths include pyridinium compounds to improve rate of copper deposition on substrates. The copper from the electroless plating baths can be plated at low temperatures and at high plating rates.

IPC 8 full level

**C23C 18/40** (2006.01)

CPC (source: CN EP KR US)

**C23C 18/1675** (2013.01 - CN); **C23C 18/30** (2013.01 - KR); **C23C 18/40** (2013.01 - CN EP KR); **C23C 18/405** (2013.01 - EP KR US)

Citation (search report)

- [X] FR 2359215 A1 19780217 - MATSUSHITA ELECTRIC IND CO LTD [JP]
- [X] US 2016312365 A1 20161027 - CORDONIER CHRISTOPHER [JP], et al
- [A] US 2015376795 A1 20151231 - CHOW ANDY LOK-FUNG [CN], et al
- [A] WO 2016035645 A1 20160310 - JAPAN PURE CHEMICAL CO LTD [JP]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 3581677 A1 20191218**; CN 110607520 A 20191224; CN 110607520 B 20210730; JP 2019218628 A 20191226; JP 6814845 B2 20210120; KR 20190142237 A 20191226; TW 202000988 A 20200101; US 2019382901 A1 20191219

DOCDB simple family (application)

**EP 19179167 A 20190607**; CN 201910468430 A 20190531; JP 2019103422 A 20190603; KR 20190069961 A 20190613; TW 108119023 A 20190531; US 201916400381 A 20190501